

component (1) is stuck as the anisotropic conductive layer to the circuit board (4) before the positional alignment and thereafter subjected to the positional alignment, and at the bonding time, the insulating resin interposed between the electronic component and the circuit board is hardened by pressurizing the electronic component against the circuit board with heat applied to the anisotropic conductive film sheet (10) while concurrently correcting the warp of the circuit board, so that the electronic component is bonded to the circuit board.

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51.(NEW) An electronic component mounting method as claimed in claim 5, wherein the gold bump that has an approximately conically shaped tip is formed on the electrode of the electronic component by means of the capillary that has a chamfer angle (θ_c) of not greater than 100° when a gold ball (96a) is formed by an electric spark at a tip of a gold wire (95) similarly to the wire bonding in forming the bump on the electronic component and a tip shape provided with no flat portion to be brought in contact with the gold ball.

52.(NEW) An electronic component mounting method as claimed in claim 11, wherein

the device (93, 193) for forming the gold ball (96a) has the capillary, which has a tip shape provided with no flat portion to be brought in contact with the gold ball and of which a chamfer angle (θ_c) is not greater than 100° , and the gold bump that has

an approximately conically shaped tip is formed on the electrode of the electronic component by the capillary.

53.(NEW) An electronic component mounting method as claimed in claim 5, wherein the bump is a bump formed by plating or printing.

54.(NEW) An electronic component mounting method as claimed in claim 8, wherein the bump is a bump formed by plating or printing.

55.(NEW) An electronic component unit as claimed in claim 19, wherein the bump is a bump formed by plating or printing.

56.(NEW) An electronic component mounting method as claimed in claim 5, wherein the anisotropic conductive layer is provided by mixing the solid insulating resin mixed with the inorganic filler with a conductive particle (10a) that has a mean diameter greater than a mean particle diameter of the inorganic filler.

57.(NEW) An electronic component mounting method as claimed in claim 8, wherein the anisotropic conductive layer is provided by mixing the solid insulating resin mixed with the inorganic filler with a conductive particle (10a) that has a mean diameter greater than a mean particle diameter of the inorganic filler.

58.(NEW) An electronic component mounting apparatus as claimed in claim 11, wherein the anisotropic conductive layer is provided by mixing the solid insulating resin mixed with the inorganic filler (6f) with a conductive particle (10a) that has a mean diameter greater than a mean particle diameter of the inorganic filler.

59.(NEW) An electronic component unit as claimed in claim 19, wherein the anisotropic conductive layer is provided by mixing the solid insulating resin mixed with the inorganic filler (6f) with a conductive particle (10a) that has a mean diameter greater than a mean particle diameter of the inorganic filler.

60.(NEW) An electronic component mounting method as claimed in claim 28, wherein the electronic component (1) has a plurality of electrodes (2), a solid insulating resin sheet (6) that has a configurational dimension smaller than an outline dimension (OL) defined by joining the plurality of electrodes (2) of the electronic component (1) is stuck as the insulating resin layer to the circuit board (4) before the positional alignment and thereafter subjected to the positional alignment, and at the bonding time, the insulating resin interposed between the electronic component and the circuit board is hardened while concurrently correcting the warp of the circuit board by pressurizing the electronic component against the circuit board with heat applied to the insulating resin sheet (6), so that the electronic component is bonded to the circuit board.